DB2130200L

## **Panasonic**

### DB2130200L

### Silicon epitaxial planar type

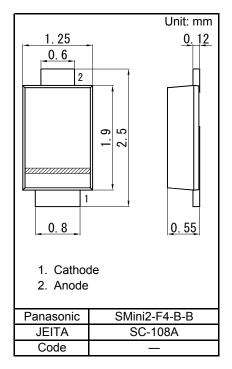
#### For rectification

#### ■ Features

- · Low forward voltage VF
- Forward current (Average) IF(AV) = 1 A rectification is possible
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: B3

#### ■ Packaging

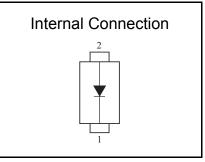
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



### ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit				
Reverse voltage	VR	30	V				
Maximum peak reverse voltage	VRM	30	V				
Forward current (Average)*1	IF(AV)	1	Α				
Non-repetitive peak forward surge current *2	IFSM	20	Α				
Junction temperature	Tj	125	°C				
Operating ambient temperature	Topr	-40 to +85	°C				
Storage temperature	Tstg	-55 to +125	°C				

Note: \*1 For embedded alumina substrate (substrate size:5 cm  $\times$  5 cm)



Established: 2010-12-03 Revised: 2013-04-19

<sup>\*2 50</sup> Hz sine wave 1 cycle (Non-repetitive peak current)

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■ Electrical Characteristics Ta = 25 °C ± 3 °C

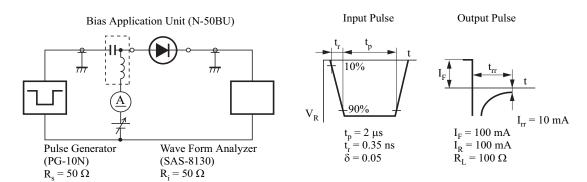
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF1	IF = 0.7 A			0.36	V
	VF2	IF = 1.0 A			0.38	
Reverse current	IR	VR = 30 V			1200	μA
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		48		pF
Reverse recovery time *1	trr	IF = IR = 100 mA		18		ns
	uı	Irr = 10 mA, RL = 100 $\Omega$		10		

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*1 trr test circuit

Established: 2010-12-03

Revised

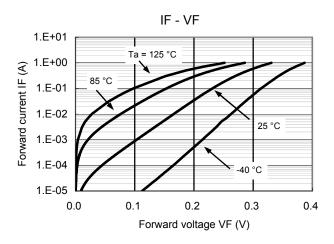
: 2013-04-19

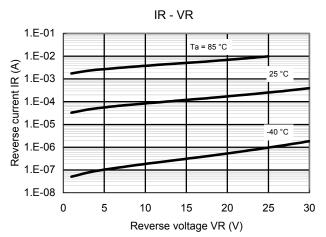


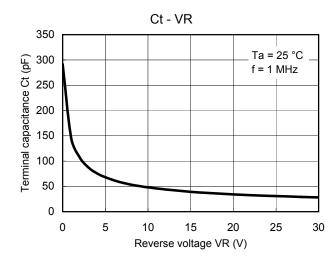
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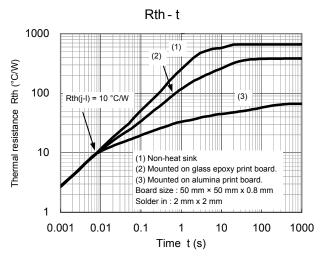
## **Panasonic**

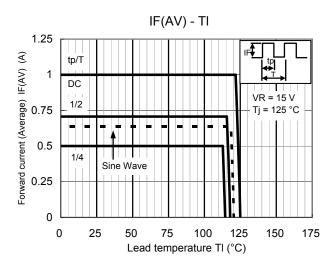
### Technical Data ( reference )

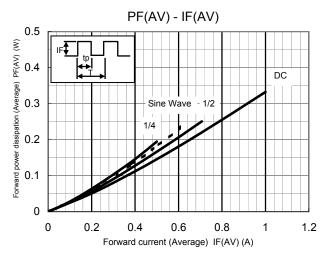












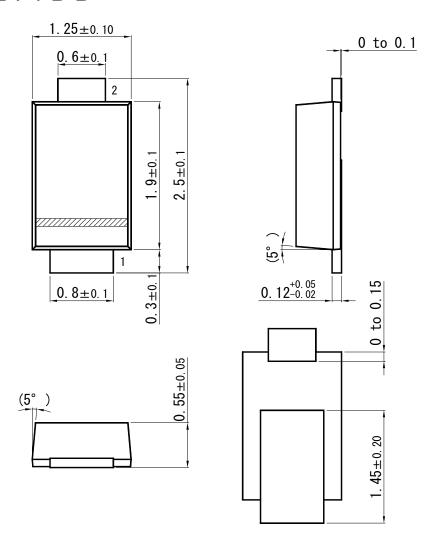
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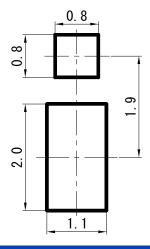
# **Panasonic**

SMini2-F4-B-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



Established: 2010-12-03 Revised: 2013-04-19

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